80V NPN MEDIUM POWER TRANSISTORS IN SOT89

Description

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Leads, Solderable per MIL-STD-202 Method 208 e3
- Weight: 0.055 grams (Approximate)

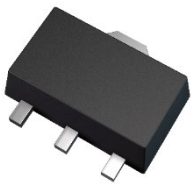
Features

- BV_{CEO} > 80V
- I_C = 1A High Continuous Collector Current
- I_{CM} = 2.0A Peak Pulse Current
- Low Saturation Voltage $V_{CE(sat)}$ < 500mV @ 0.5A
- Epitaxial Planar Die Construction
- Complementary PNP types: BCX5316Q
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. "Green" Device (Note 3)**
- **The BCX5616Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF16949 certified facilities.**
  https://www.diodes.com/quality/product-definitions/

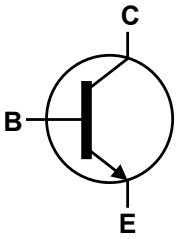
Applications

- Automotive
- Medium Power Switching or Amplification Applications
- AF Driver and Output Stages

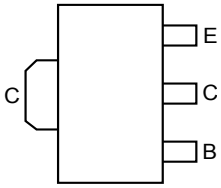
SOT89



Top View



Device Symbol



Top View
Pin-Out

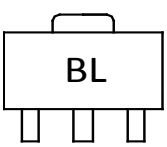
Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BCX5616QTA	Automotive	BL	7	12	1,000
BCX5616QTC	Automotive	BL	13	12	4,000

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

SOT89



BL = Product Type Marking Code

Absolute Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V_{CEO}	80	V
Emitter-Base Voltage	V_{EBO}	6	V
Continuous Collector Current	I_C	1	A
Peak Pulse Collector Current	I_{CM}	2.0	
Continuous Base Current	I_B	100	mA
Peak Pulse Base Current	I_{BM}	200	

Thermal Characteristics (@ T_A = +25°C, unless otherwise specified.)

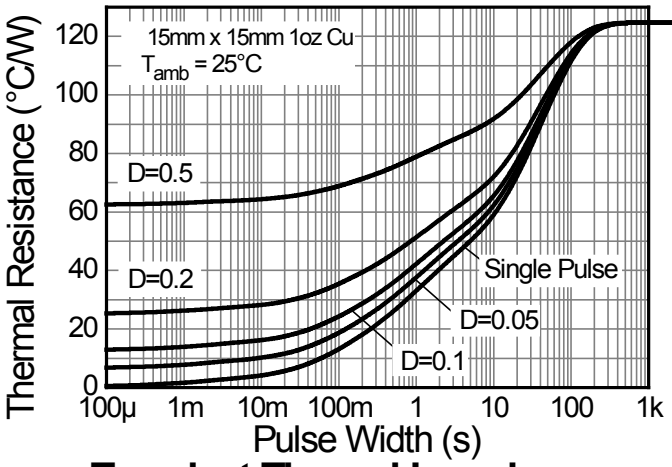
Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 5)	P_D	1	W
	(Note 6)		1.5	
	(Note 7)		2.0	
Thermal Resistance, Junction to Ambient Air	(Note 5)	$R_{\theta JA}$	125	°C/W
	(Note 6)		83	
	(Note 7)		60	
Thermal Resistance, Junction to Lead	(Note 8)	$R_{\theta JL}$	13	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

ESD Ratings (Note 9)

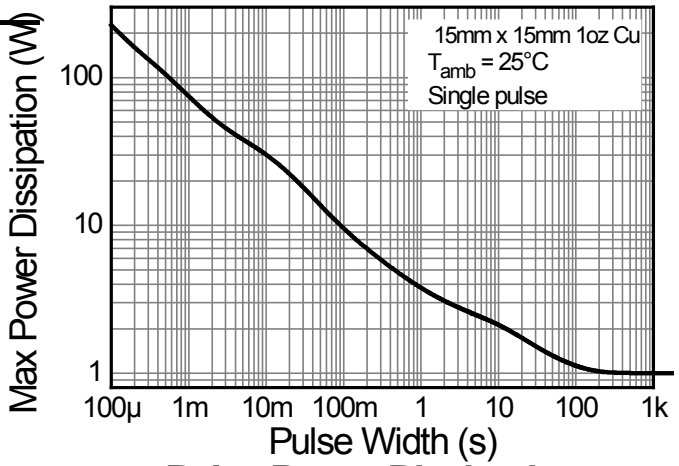
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes:
5. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
6. Same as note (6), except the device is mounted on 25mm x 25mm 1oz copper.
7. Same as note (6), except the device is mounted on 50mm x 50mm 1oz copper.
8. Thermal resistance from junction to solder-point (on the exposed collector pad).
9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

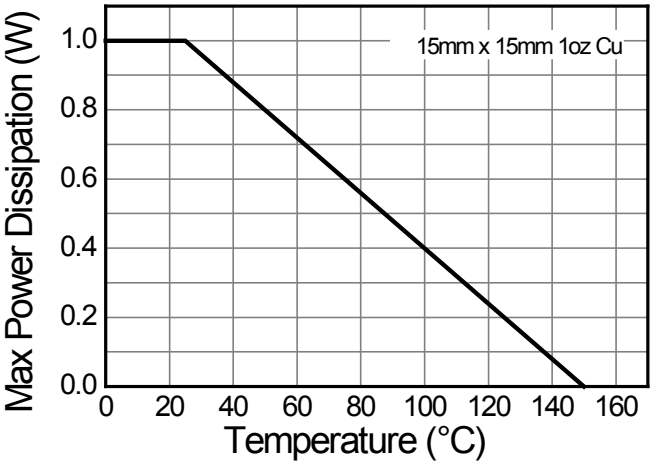
Thermal Characteristics and Derating Information



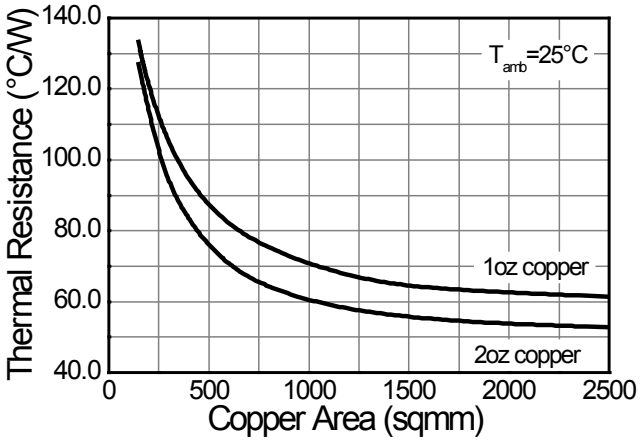
Transient Thermal Impedance

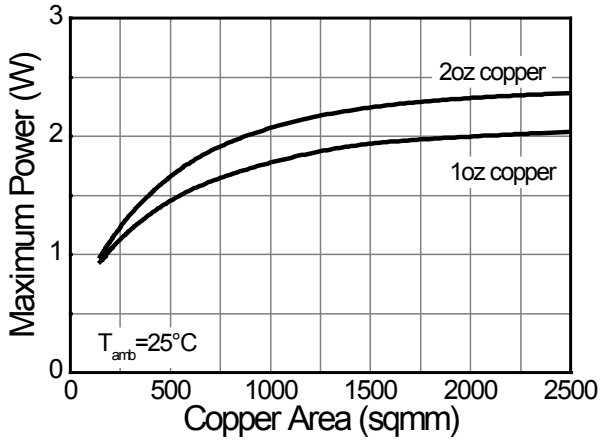


Pulse Power Dissipation



Derating Curve





Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	100	—	—	V	I_C = 100µA
Collector-Emitter Breakdown Voltage (Note 10)	BV_{CEO}	80	—	—	V	I_C = 10mA
Emitter-Base Breakdown Voltage	BV_{EBO}	6	—	—	V	I_E = 100µA
Collector Cut-off Current	I_{CBO}	— —	— —	0.1 20	µA	V_{CB} = 30V V_{CB} = 30V, T_A = +150°C
Emitter Cut-off Current	I_{EBO}	—	—	20	nA	V_{EB} = 5V
Static Forward Current Transfer Ratio (Note 10)	h_{FE}	25 100 25	— — —	— 250 —	—	I_C = 5mA, V_{CE} = 2V I_C = 150mA, V_{CE} = 2V I_C = 500mA, V_{CE} = 2V
Collector-Emitter Saturation Voltage (Note 10)	$V_{CE(sat)}$	—	—	0.5	V	I_C = 500mA, I_B = 50mA
Base-Emitter Turn-On Voltage (Note 10)	$V_{BE(on)}$	—	—	1.0	V	I_C = 500mA, V_{CE} = 2V
Transition Frequency	f_T	150	—	—	MHz	I_C = 50mA, V_{CE} = 10V f = 100MHz
Output Capacitance	C_{obo}	—	—	25	pF	V_{CB} = 10V, f = 1MHz

Notes: 10. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.

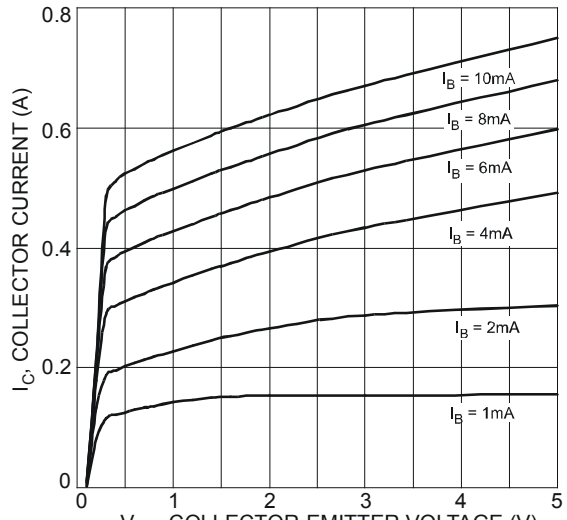


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

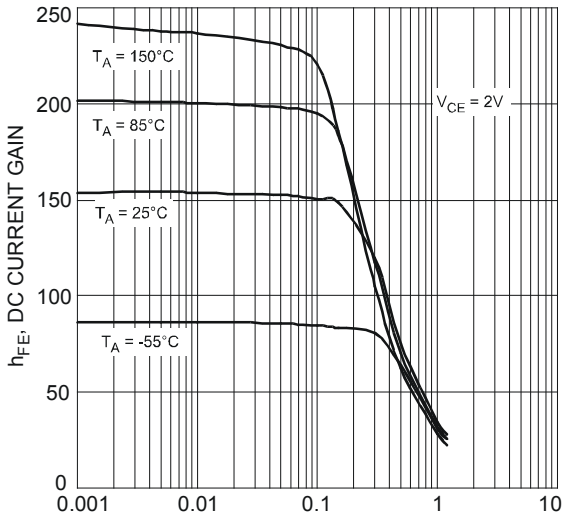


Fig. 2 Typical DC Current Gain vs. Collector Current

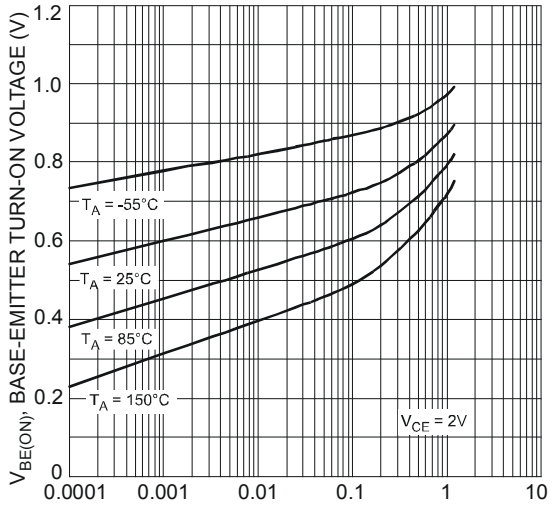


Fig. 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

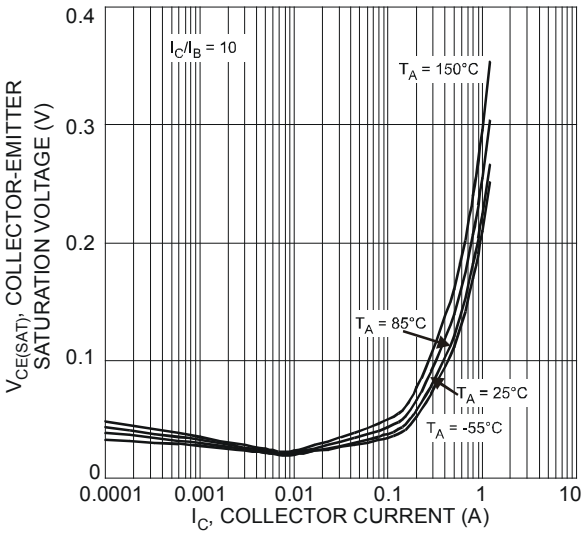


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

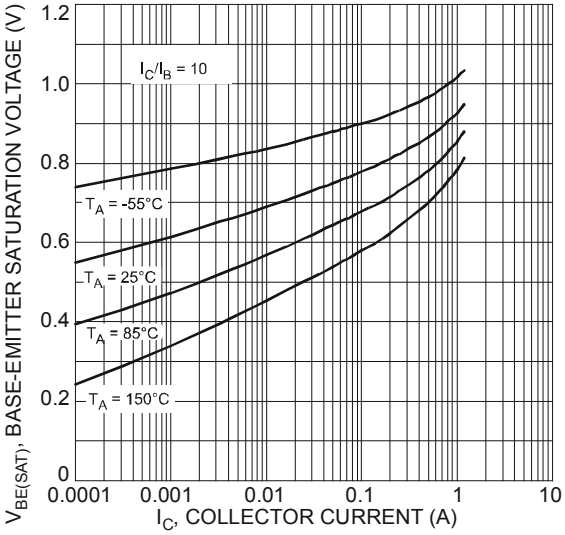


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

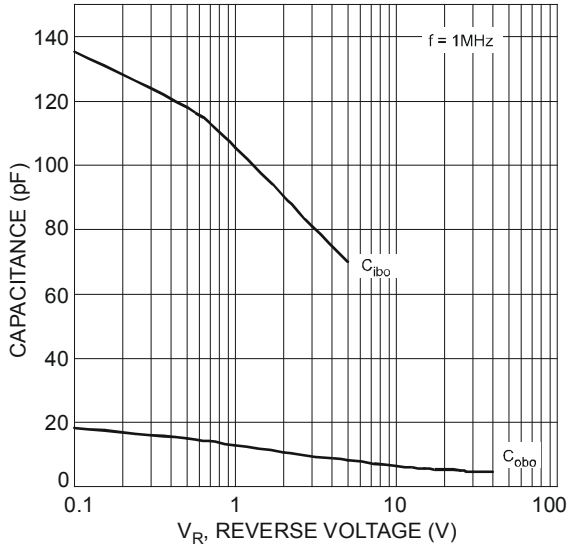


Fig. 6 Typical Capacitance Characteristics

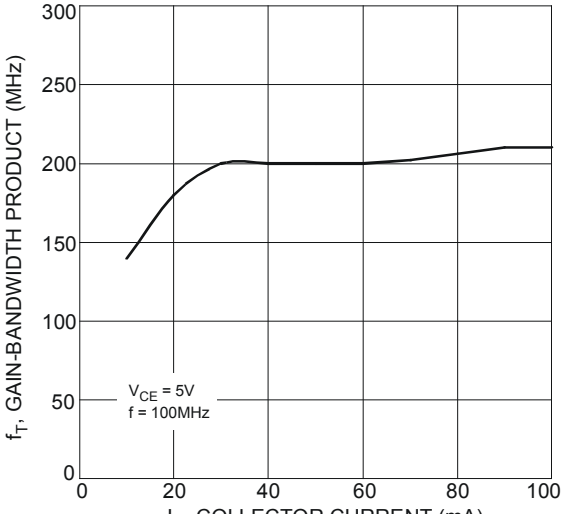
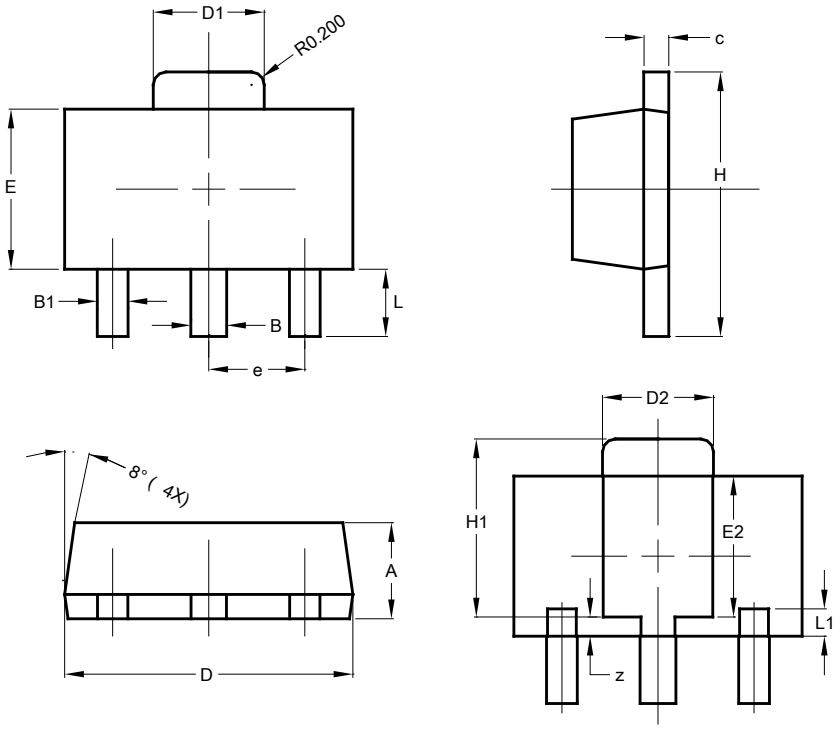


Fig. 7 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

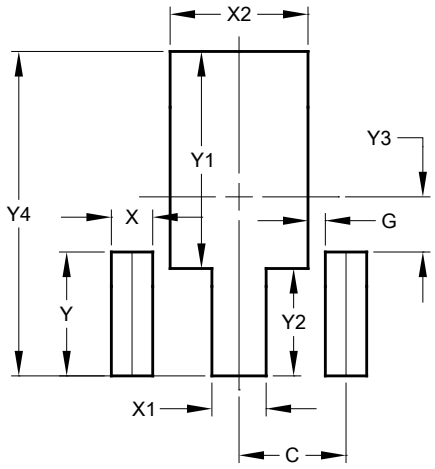
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT89			
Dim	**Min**	**Max**	**Typ**
A	1.40	1.60	1.50
B	0.50	0.62	0.56
B1	0.42	0.54	0.48
c	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.62	1.83	1.733
D2	1.61	1.81	1.71
E	2.40	2.60	2.50
E2	2.05	2.35	2.20
e	-	-	1.50
H	3.95	4.25	4.10
H1	2.63	2.93	2.78
L	0.90	1.20	1.05
L1	0.327	0.527	0.427
z	0.20	0.40	0.30
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
C	1.500
G	0.244
X	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

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